

Claim 1 (currently amended): A multilayer printed wiring board comprising:

a core substrate;

a first conductor layer formed on said core substrate;

an interlayer insulating layer ~~[[and]]~~ formed over said first ~~[[a]]~~ conductor layer
~~formed on a~~ and said core substrate, the conductor layer being electrically connected through
~~a via hole;~~

a second conductor layer formed on said interlayer insulating layer; and

a via hole structure electrically connecting said first and second conductor layers,

wherein said first ~~a thickness of the~~ conductor layer on said core substrate has a
thickness which is larger than a thickness of ~~[[the]]~~ said second conductor layer on ~~[[the]]~~
said interlayer insulating layer.

Claim 2 (currently amended): The ~~[[A]]~~ multilayer printed wiring board comprising:
~~an interlayer insulating layer and a conductor layer formed on a core substrate, the conductor~~
~~layer being electrically connected through a via hole; according to Claim 1,~~ wherein said ~~if a~~
thickness of ~~[[the]]~~ said first conductor layer on said core substrate is $\alpha 1$, said ~~and a thickness~~
of ~~[[the]]~~ said second conductor layer on ~~[[the]]~~ said interlayer insulating layer is $\alpha 2$, and $\alpha 1$
and $\alpha 2$ satisfy $\alpha 2 < \alpha 1 \leq 40\alpha 2$.

Claim 3 (previously presented): The multilayer printed wiring board according to
claim 1, wherein said $\alpha 1$ satisfies $2\alpha 2 \leq \alpha 1 \leq 40\alpha 2$.

Claim 4 (previously presented): The multilayer printed wiring board according to
claim 1, wherein the conductor layer of said core substrate is the conductor layer for a power
supply layer or the conductor layer for an earth.

Claim 5 (previously presented): The multilayer printed wiring board according to
claim 1, wherein a capacitor is mounted on a surface of the multilayer printed wiring board.

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Claim 6 (currently amended): A multilayer printed wiring board comprising:

a core substrate;

a conductor layer formed on said core substrate; and

an interlayer insulating layer and a formed over said conductor layer formed on a and
said core substrate, the conductor layer being electrically connected through a via hole;

wherein said core substrate is a multilayer core substrate comprising not less than three layers including ~~a thick conductor layer~~ as an inner conductor layer[[;]], said inner conductor layer of said core substrate has a thickness which is larger than a thickness of said conductor layer on a surface of said core substrate, and ~~the conductor layer~~ as the inner conductor layer and the conductor layer on a surface of said core substrate are electrically connected through a via hole and comprise the conductor layers for a power supply layer or ~~the conductor layers~~ for an earth.

Claim 7 (currently amended): A multilayer printed wiring board comprising:

a core substrate;

a conductor layer formed on said core substrate; and

an interlayer insulating layer and a formed over said conductor layer formed on a and
said core substrate, the conductor layer being electrically connected through a via hole;

wherein said core substrate is a multilayer core substrate comprising not less than three layers including ~~a thick conductor layer~~ as an inner conductor layer[[;]], said inner conductor layer of said core substrate has a thickness which is larger than a thickness of said conductor layer on a surface of said core substrate, [[and]] said a conductor layer as an inner conductor layer of said core substrate is the conductor layer as a power supply layer or [[the]] conductor layer as for an earth, said inner conductor layer of said core substrate and said conductor layer on a surface of said core substrate are electrically connected through a via

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hole and ~~that a~~ said conductor layer on a surface layer of said core substrate comprises a signal line.

Claim 8 (previously presented): A multilayer printed wiring board according to claim 6, wherein a thickness of the conductor layer on said core substrate is larger than a thickness of the conductor layer on the interlayer insulating layer.

Claim 9 (previously presented): The multilayer printed wiring board according to claim 6, wherein the conductor layer as the inner layer of said core substrate is not less than two conductor layers.

Claim 10 (previously presented): The multilayer printed wiring board according to claim 6, wherein said core substrate is constituted so that the conductor layer as said inner layer is formed on each surface of an electrically isolated metallic plate through a resin layer and so that said conductor layer on the surface layer is formed outside of the conductor layer as the inner layer through the resin layer.

Claim 11 (previously presented): The multilayer printed wiring board according to claim 6, wherein said core substrate comprises a thick conductor layer as the inner layer and a thin conductor layer as the conductor layer on the surface layer.

Claim 12 (previously presented): The multilayer printed wiring board according to claim 2, wherein the conductor layer of said core substrate is the conductor layer for a power supply layer or the conductor layer for an earth.

Claim 13 (previously presented): The multilayer printed wiring board according to claim 2, wherein a capacitor is mounted on a surface of the multilayer printed wiring board.

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Claim 14 (previously presented): A multilayer printed wiring board according to claim 7, wherein a thickness of the conductor layer on said core substrate is larger than a thickness of the conductor layer on the interlayer insulating layer.

Claim 15 (previously presented): The multilayer printed wiring board according to claim 7, wherein the conductor layer as the inner layer of said core substrate is not less than two conductor layers.

Claim 16 (previously presented): The multilayer printed wiring board according to claim 7, wherein said core substrate is constituted so that the conductor layer as said inner layer is formed on each surface of an electrically isolated metallic plate through a resin layer and so that said conductor layer on the surface layer is formed outside of the conductor layer as the inner layer through the resin layer.

Claim 17 (previously presented): The multilayer printed wiring board according to claim 7, wherein said core substrate comprises a thick conductor layer as the inner layer and a thin conductor layer as the conductor layer on the surface layer.